



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Smith et al  
Serial No.: 10/775,718  
Filed: February 9, 2004  
Customer No.: 33123  
For: METHOD AND APPARATUS FOR  
SELF-REFERENCED WAFER  
STAGE POSITIONAL ERROR  
MAPPING

CERTIFICATE OF MAILING

I hereby certify that this correspondence and the attached papers are being deposited with the United States Postal Service with sufficient postage as first class mail on the date indicated below in an envelope addressed to:

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

4-6-04  
Date

TRANSMITTAL LETTER

Commissioner for Patents  
PO Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Transmitted herewith are an Information Disclosure Statement and Form PTO-1449 (4 pages). Because this Information Disclosure Statement is filed prior to receipt of a first office action on the merits in the above-referenced application, no fee is due. However, should it be determined that a fee for filing these papers is required, the Commissioner is authorized to charge Deposit Account No. 05-1213, as stated below:

[X] The Commissioner is hereby authorized to charge any fees that may be due under 37 C.F.R. §§ 1.16-1.17 in connection with this paper or with this application during its entire pendency to Deposit Account No. 05-1213. A copy of this sheet is enclosed.

Respectfully submitted,  
HELLER, EHRMAN, WHITE & McAULIFFE LLP

By:   
David A. Hall  
Registration No. 32,233

Attorney Docket No. 38203-6082B  
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**INFORMATION DISCLOSURE STATEMENT  
IN ACCORDANCE WITH 37 C.F.R. §§ 1.97-1.98**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Because this Information Disclosure Statement is filed prior to receipt of a First Office Action on the merits of the above-captioned application, a fee for filing this statement should not be due. If, however, it is determined that a fee is due, then any fees that may be due in connection with filing this paper may be charged to Deposit Account No. 50-1213.

In accordance with the duty of disclosure imposed by 37 C.F.R. § 1.56 to inform the Patent Office of all material references known by Applicant or Applicants' representative, this Information Disclosure Statement prepared in accordance with 37 C.F.R. §§ 1.97-1.98 is hereby submitted. Attached is a Form PTO-1449 (4 pages) for filing in connection with the above cited continuation application.

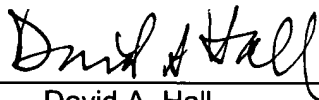
In accordance with 37 C.F.R. § 1.98(d), copies of the cited documents are not provided, as they have been previously provided in connection with the related case of U.S. Application Serial No. 09/891,699 filed June 26, 2001 on which this application relies (35 U.S.C. § 120) for an earlier effective filing date. The earlier-filed '699 Application claims benefit of priority to U.S. Provisional Application Serial No. 60/254,413 filed on December 8, 2000.

Although these documents and information are made known to the Patent and Trademark Office in compliance with Applicants' duty of disclosure, such disclosure is not to be construed as an admission by Applicants or Applicants' representative that any of the references, singly or in any combination thereof, is effective as prior art against the subject

application. In accordance with 37 C.F.R. § 1.97(h), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 C.F.R. § 1.56(b) exists.

Applicants respectfully request that the Examiner review the foregoing references and request that they be made of record in the file history of the above-captioned application.

Respectfully submitted,  
HELLER, EHRMAN, WHITE & McAULIFFE LLP

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Registration No. 32,233

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO.:  
38203-6082BSERIAL NO.:  
10/775,718

## INFORMATION DISCLOSURE STATEMENT

UNDER 37 CFR §1.56, §1.97, and §1.98

PTO-1449 FORM

Sheet 1 of 4

APPLICANTS: Smith et al

FILING DATE: 02/09/04

GROUP ART UNIT: Unknown

## U.S. PATENT DOCUMENTS

† EX'R INITIAL	*REF. #	PATENT NUMBER	DATE	NAME	U.S. CLASS/ SUBCLASS	FILING DATE (If appropriate)
		4,757,207	07/12/88	Chappelow et al	250/491.1	
		4,861,148	08/29/89	Santo <i>et al.</i>	350/505	
		4,929,083	05/29/90	Brunner	356/123	
		5,124,927	06/23/92	Hopewell et al	250/491.1	
		5,262,257	11/16/93	Fukuda et al	250/492.2	
		5,285,236	02/08/94	Jain	355/53	
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		5,444,538	08/22/95	Pellegrini	356/401	
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EXAMINER'S SIGNATURE

DATE CONSIDERED

† EXAMINER: Initial if reference is considered, whether or not citation is in conformance with MPEP 609. Line through citation if not in conformance and not considered. *Include copy of this form in next communication to applicant.*

\* If an asterisk is placed beside the reference number, a copy is not provided because the reference was previously cited by or submitted to the PTO in a prior application that is identified in the statement and relied upon for an earlier filing date under 35 U.S.C. 120. 37 C.F.R. 1.98(d).

TITLE: METHOD AND APPARATUS FOR SELF-REFERENCED WAFER STAGE POSITIONAL ERROR MAPPING

<b>IN THE UNITED STATES PATENT AND TRADEMARK OFFICE</b>  <b>INFORMATION DISCLOSURE STATEMENT</b> UNDER 37 CFR §1.56, §1.97, and §1.98 <b>PTO-1449 FORM</b>  Sheet 2 of 4	ATTORNEY DOCKET NO.: 38203-6082B	SERIAL NO.: 10/775,718
	APPLICANTS: Smith et al	
	FILING DATE: 02/09/04	GROUP ART UNIT: Unknown

FOREIGN PATENT DOCUMENTS					
† EX'R INITIAL	*REF. #				TRANSLATION (YES/NO)
			N/A	N/A	

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† EX'R INITIAL	*REF. #	CITATION (Author, Article Title, Journal/Book Title, Date, Pertinent Pages, etc.)
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SD 656917 v1 (38203.6082)

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